

**1M-BIT CMOS FAST STATIC RAM
128K-WORD BY 8-BIT**

Description

The μ PD431008 is a high speed, low power, 1 048 576 bits (131 072 words by 8 bits) CMOS static RAM.

The μ PD431008 is packed in 32-pin plastic SOJ.

Feature

- 131 072 words by 8 bits organization
- Fast access time 15, 17, 20 ns (MAX.)
- Output buffers control: $\overline{OE}$
- Common I/O using three state outputs
- Fully static operation: no clock or refreshing to operate
- TTL compatible: all inputs and outputs
- Single +5 V power supply

Ordering Information

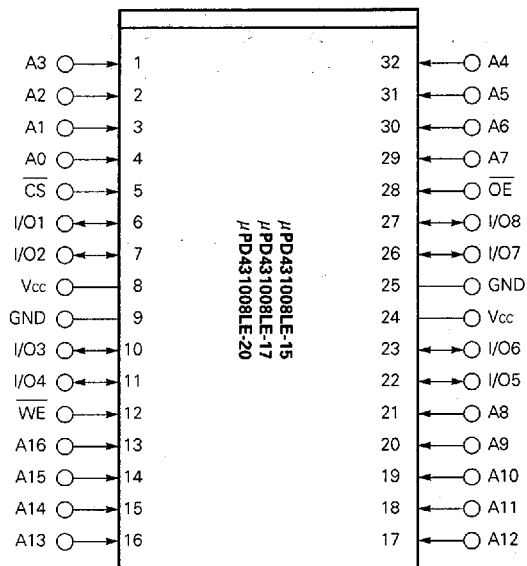
Part number	Package	Access time ns (MAX.)	Operating supply current mA (MAX.)	Standby supply current mA (MAX.)	Quality grade
μ PD431008LE-15	32-pin plastic SOJ (400 mil)	15	160	10	Standard
μ PD431008LE-17		17	150		
μ PD431008LE-20		20	140		

Remark Operating supply current is 120 mA (MAX.) when this product is used at 50ns cycle time.

Please refer to "Quality grade on NEC Semiconductor Devices" (Document number IEI-1209) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

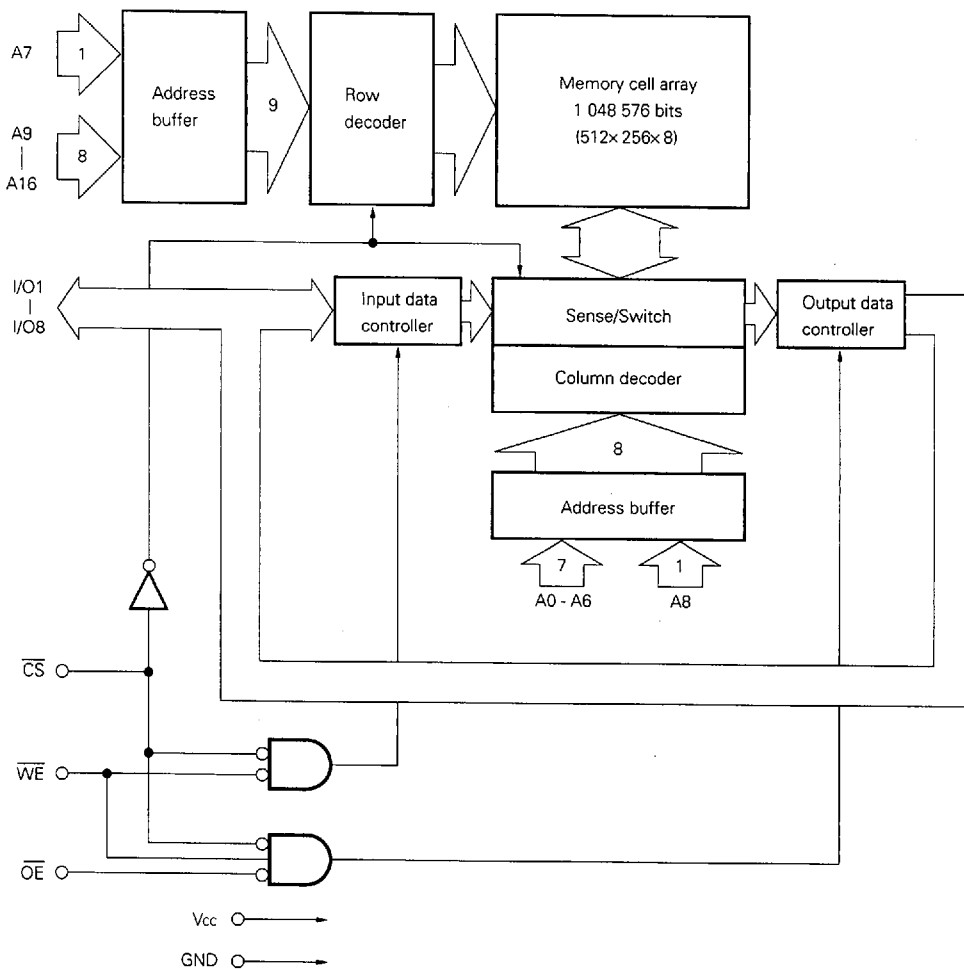
Pin Configuration (Marking Side)

32-Pin Plastic SOJ (400 mil)



A0 – A16 : Address Inputs
 I/O1 – I/O8 : Data Inputs/Outputs
 CS : Chip Select
 WE : Write Enable
 OE : Output Enable
 Vcc : Power Supply
 GND : Ground

Block Diagram



Truth Table

$\overline{CS}$	$\overline{OE}$	$\overline{WE}$	Mode	I/O	Supply current
H	X	X	Not selected	Hi-Z	I_{SB}
L	L	H	Read	D_{OUT}	I_{CC}
L	X	L	Write	D_{IN}	
L	H	H	Output disable	Hi-Z	

Remark X : Don't care

Electrical Specifications

Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply voltage	V _{CC}	-0.5 ^{Note} to +7.0	V
Input/Output voltage	V _I	-0.5 ^{Note} to V _{CC} +0.5	V
Operating temperature	T _{opt}	0 to +70	°C
Storage temperature	T _{stg}	-55 to +125	°C

Note -3.0 V (MIN.) (Pulse width: 10 ns)

Recommended Operating Conditions

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply voltage	V _{CC}	4.5	5.0	5.5	V
High level input voltage	V _{IH}	2.2		V _{CC} +0.5	V
Low level input voltage	V _{IL}	-0.5 ^{Note}		+0.8	V
Ambient temperature	T _a	0		+70	°C

Note -3.0 V (MIN.) (Pulse width: 10 ns)

DC Characteristics (Recommended operating conditions unless otherwise noted)

Parameter	Symbol	Test conditions	MIN.	TYP.	MAX.	Unit
Input leakage current	I _{LI}	V _{IN} = 0 V to V _{CC}	-2		+2	μA
Output leakage current	I _{LO}	V _{IO} = 0 V to V _{CC} , $\overline{CS} = V_{IH}$ or $\overline{OE} = V_{IH}$ or $\overline{WE} = V_{IL}$	-2		+2	μA
Operating supply current	I _{CC}	$\overline{CS} = V_{IL}$, I _{VO} = 0 mA	Cycle time: 15 ns		160	mA
			Cycle time: 17 ns		150	
			Cycle time: 20 ns		140	
			Cycle time: 50 ns		120	
Standby supply current	I _{SB}	$\overline{CS} = V_{IH}$, V _{IN} = V _{IH} or V _{IL}			30	mA
	I _{SB1}	V _{CC} - 0.2 V ≤ $\overline{CS}$, V _{IN} ≤ 0.2 V or V _{CC} - 0.2 V ≤ V _{IN}			10	
High level output voltage	V _{OH}	I _{OH} = -4.0 mA	2.4			V
Low level output voltage	V _{OL}	I _{OL} = 8 mA			0.4	V

Remark V_{IN}: Input voltage

Capacitance (T_a = +25 °C, f = 1 MHz)

Parameter	Symbol	Test conditions	MIN.	TYP.	MAX.	Unit
Input capacitance	C _{IN}	V _{IN} = 0 V			6	pF
Input/Output capacitance	C _{IO}	V _{IO} = 0 V			8	pF

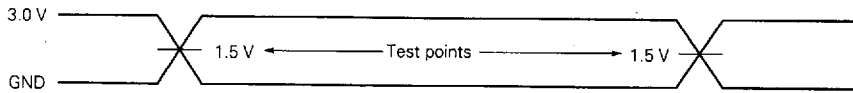
Remark 1. V_{IN}: Input voltage

2. These parameters are periodically sampled and not 100 % tested.

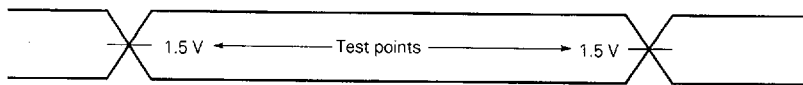
AC Characteristics (Recommended operating conditions unless otherwise noted)

AC Test Conditions

Input waveform (Rise/fall time ≤ 3 ns)



Output waveform



Output load

AC Characteristics directed with the note should be measured with the output load shown in Fig. 1 or Fig. 2.

Fig. 1

(For tAA, tACS, tOE, tOH)

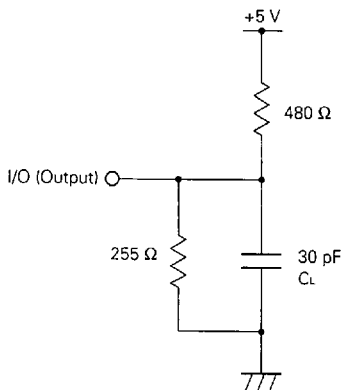
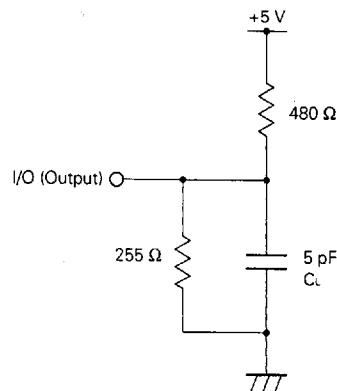


Fig. 2

(For tCHZ, tCLZ, tOHZ, tOLZ, tWHZ, tOW)



Remark C_L includes capacitances of the probe and jig, and stray capacitances.

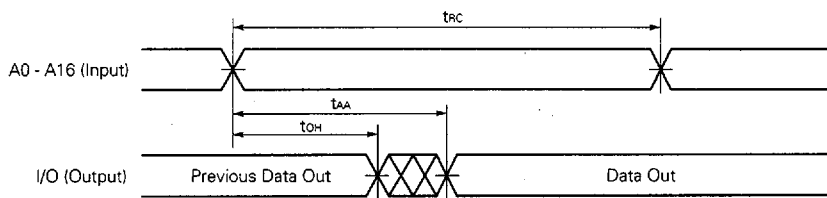
Read Cycle

Parameter	Symbol	μ PD431008LE-15		μ PD431008LE-17		μ PD431008LE-20		Unit	Condition
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Read cycle time	t_{RC}	15		17		20		ns	
Address access time	t_{AA}		15		17		20	ns	Note 1.
$\overline{CS}$ access time	t_{ACS}		15		17		20	ns	
$\overline{OE}$ access time	t_{OE}		8		9		10	ns	
Output hold from address change	t_{OH}	5		5		5		ns	Note 2.
$\overline{CS}$ to output in low-Z	t_{CLZ}	5		5		5		ns	
$\overline{OE}$ to output in low-Z	t_{OLZ}	1		1		1		ns	
$\overline{CS}$ to output in high-Z	t_{CHZ}		7		7		7	ns	
$\overline{OE}$ to output in high-Z	t_{OHZ}		7		7		7	ns	

Note 1. See the output load shown in Fig. 1.

2. See the output load shown in Fig. 2.

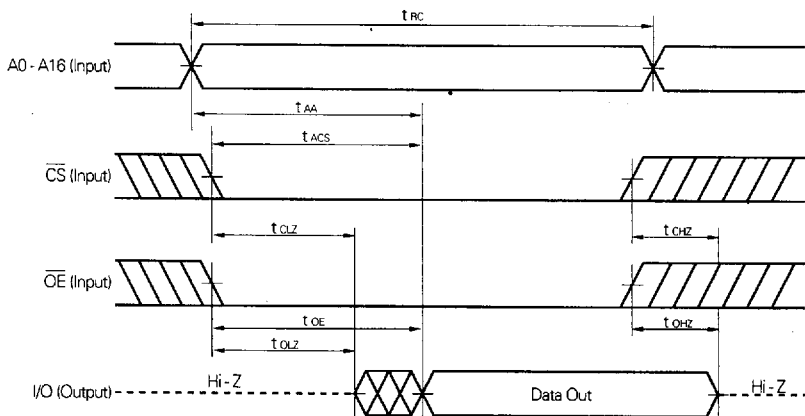
Read Cycle Timing Chart 1 (Address Access)



Remark 1. In read cycle, $\overline{WE}$ should be fixed to high level.

2. $\overline{CS} = \overline{OE} = V_{IL}$

Read Cycle Timing Chart 2 ($\overline{CS}$ Access)



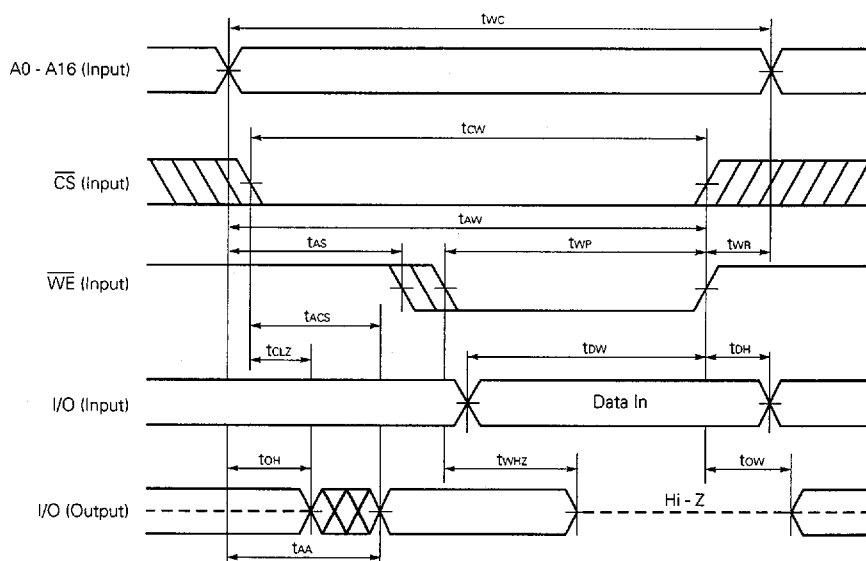
Caution Address valid prior to or coincident with $\overline{CS}$ low level input.

Remark In read cycle, $\overline{WE}$ should be fixed to high level.

Write Cycle

Parameter	Symbol	μ PD431008LE-15		μ PD431008LE-17		μ PD431008LE-20		Unit	Condition
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Write cycle time	twc	15		17		20		ns	
$\overline{\text{CS}}$ to end of write	tcw	10		11		12		ns	
Address valid to end of write	taw	9		11		12		ns	
Write pulse width	twp	9		10		10		ns	
Data valid to end of write	tdw	8		9		10		ns	
Data hold time	tDH	0		0		0		ns	
Address setup time	tAS	0		0		0		ns	
Write recovery time	tWR	0		0		0		ns	
$\overline{\text{WE}}$ to output in high-Z	tWHZ		7		7		7	ns	Note
Output active from end of write	tOW	3		3		3		ns	

Note See the output load shown in Fig. 2.

Write Cycle Timing Chart 1 ($\overline{\text{WE}}$ Controlled)

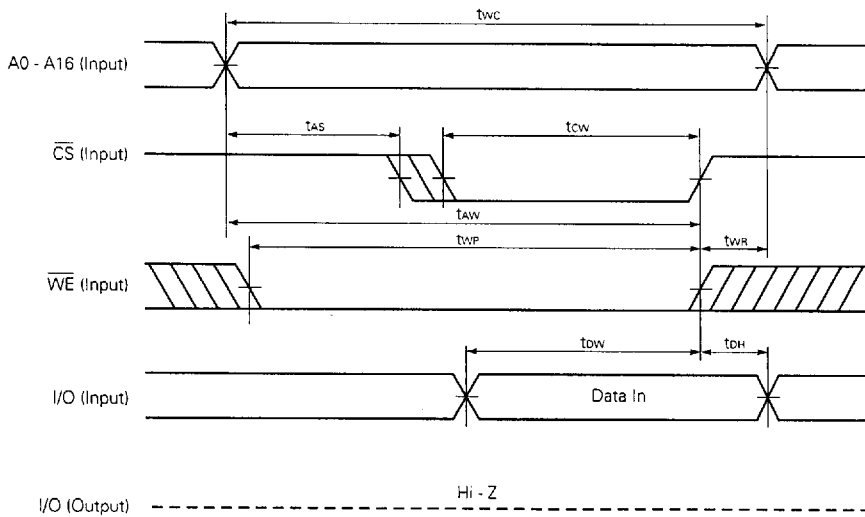
Caution $\overline{\text{CS}}$ or $\overline{\text{WE}}$ should be fixed to high level during address transition.

Remark 1. Write operation is done during the overlap time of a low level $\overline{\text{CS}}$ and a low level $\overline{\text{WE}}$.

2. During t_{WHZ} , I/O pins are in the output state, therefore the input signals of opposite phase to the output must not be applied.

3. When $\overline{\text{WE}}$ is at low level, the I/O pins are always Hi-Z. When $\overline{\text{WE}}$ is at high level, read operation is executed. Therefore $\overline{\text{OE}}$ should be at high level to make the I/O pins Hi-Z.

Write Cycle Timing Chart 2 ($\overline{\text{CS}}$ Controlled)

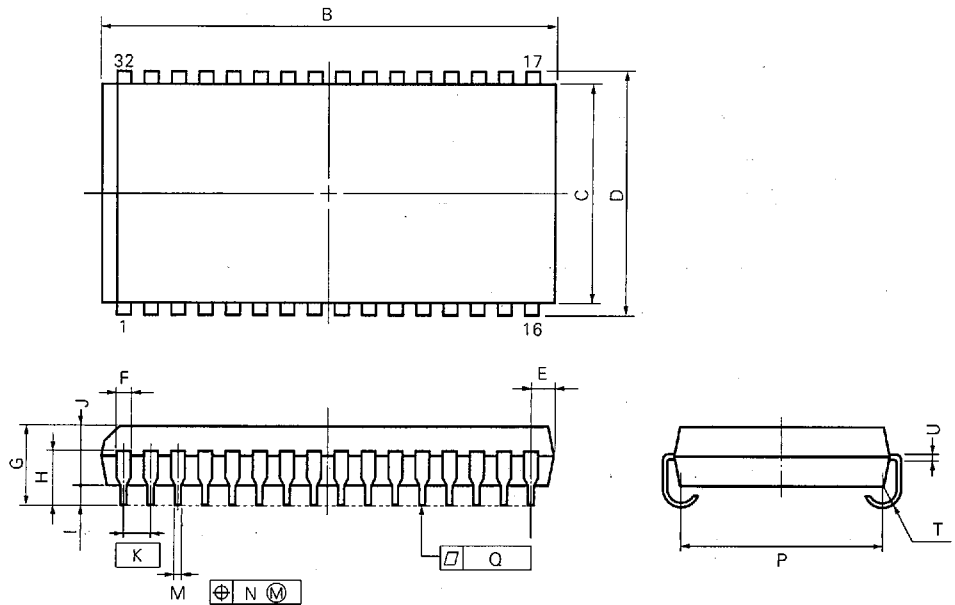


Caution $\overline{\text{CS}}$ or $\overline{\text{WE}}$ should be fixed to high level during address transition.

Remark Write operation is done during the overlap time of a low level $\overline{\text{CS}}$ and a low level $\overline{\text{WE}}$.

Package Drawing

32 PIN PLASTIC SOJ (400 mil)



NOTE

Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

P32LE-400A

ITEM	MILLIMETERS	INCHES
B	21.06±0.2	0.829±0.008
C	10.16	0.400
D	11.18±0.2	0.440±0.008
E	1.005±0.1	0.040 ^{+0.004} _{-0.005}
F	0.74	0.029
G	3.5±0.2	0.138±0.008
H	2.545±0.2	0.100±0.008
I	0.8 MIN.	0.031 MIN.
J	2.6	0.102
K	1.27 (T.P.)	0.050 (T.P.)
M	0.40±0.10	0.016 ^{+0.004} _{-0.005}
N	0.12	0.005
P	9.4±0.20	0.370±0.008
Q	0.1	0.004
T	R 0.85	R 0.033
U	0.20 ^{+0.10} _{-0.05}	0.008 ^{+0.004} _{-0.002}

RECOMMENDED SOLDERING CONDITIONS

Please consult with our sales offices for soldering conditions of the μPD431008.

TYPE OF SURFACE MOUNT DEVICE

μPD431008LE: 32-pin plastic SOJ (400 mil)